

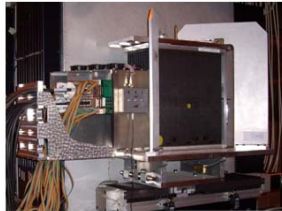
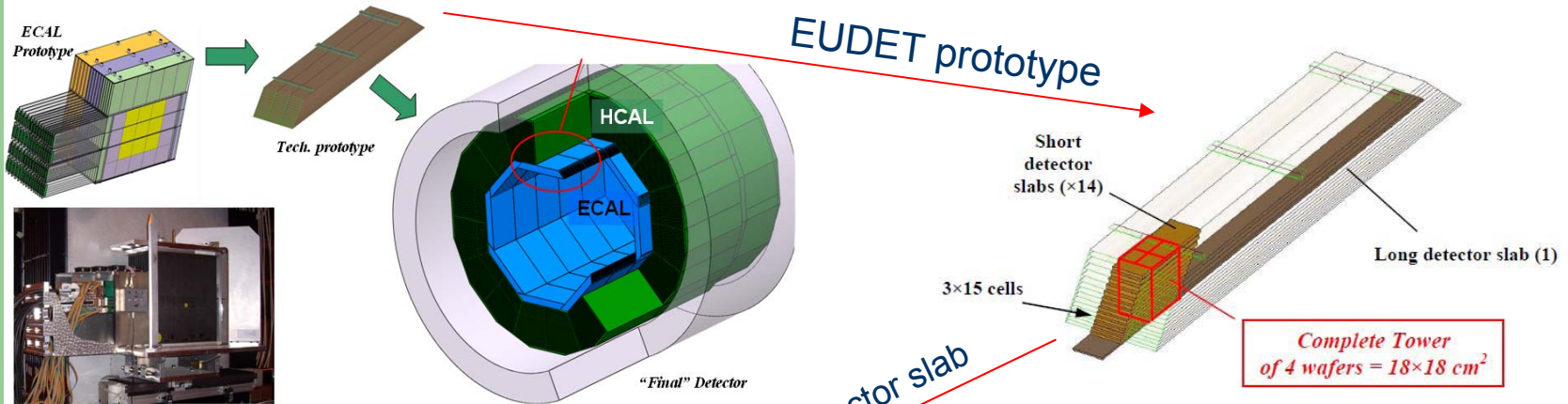


**Interconnection of ASUs  
CALICE meeting at CERN  
21 May 2011  
R.Poeschl P.Cornebise**

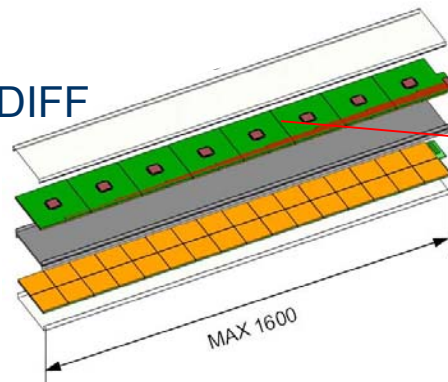
# Contents

- 1 Introduction
- 2 Current method of interconnection
- 3 PCB FEV interconnection with ACF 3M
  - 3.1 First test results from 3M Beauchamps (95)
  - 3.2 Second tests results from 3M Beauchamps
  - 3.3 Next steps

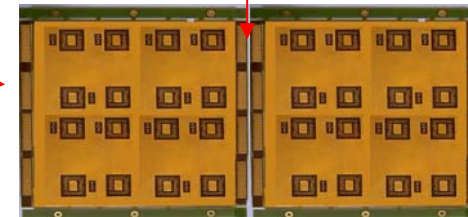
# 1 Introduction



With:  
7 ASUs+1DIFF



**This presentation focuses on the ASUs interconnections study**



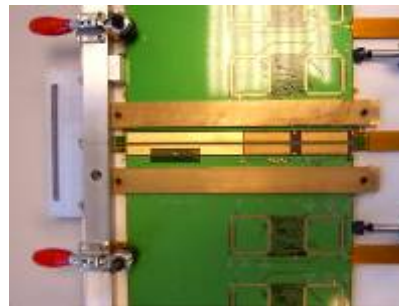
1111µm

## 2

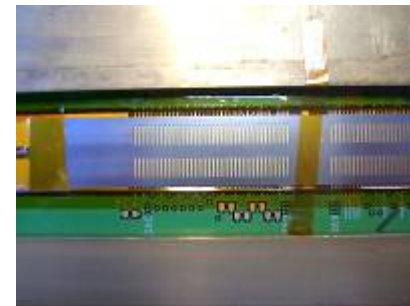
# Current method of interconnection



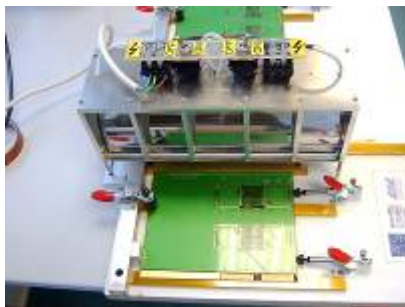
Kapton comb 1 connector



Solder bench



Silk screen for  
Manual solder paste laying  
(very delicate operation)



Halogen lamp for the solder  
200°C for 2.30 minutes

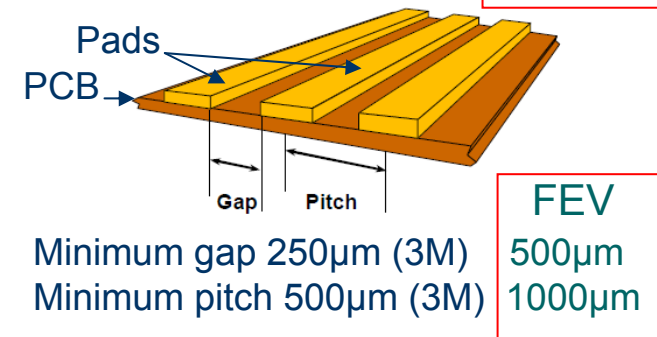
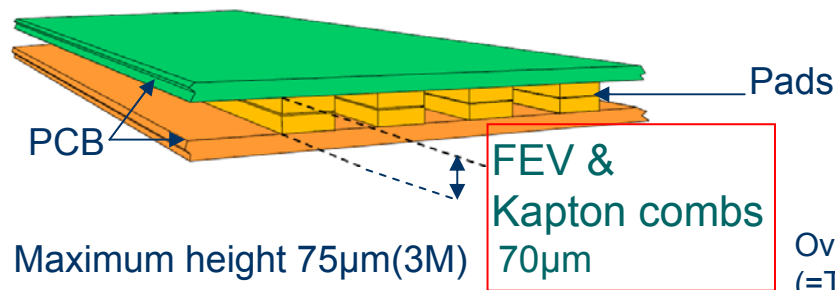


We developed this method with the Cambridge University  
and used for interconnect 8 FEV temp



# 3 PCB FEV interconnection with **ACF 3M** **Anisotropic Conductive Film** adhesives **ACF 7303 use characteristics**

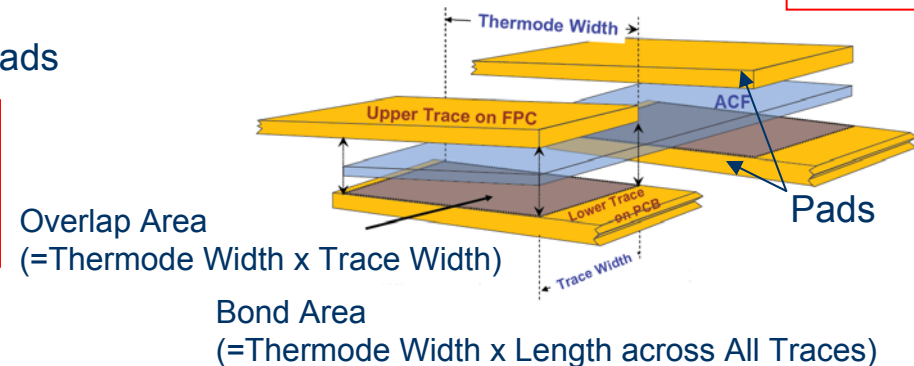
## Meet specification for the ACF employment



The ACF technology is used to:  
 -Flat screen  
 -Laptop  
 -Smartphone...

Minimum Pad Overlap = 0.75mm<sup>2</sup> (3M)

FEV  
 2.5mm<sup>2</sup>



## General Properties of ACF 7303

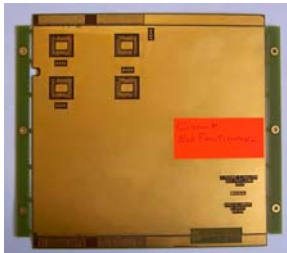
Adhesive Type: Epoxy/Acrylate Blend  
 Particle Type : Silver-coated glass  
 Particle Size : 43 µm  
 Liner Type: Polyester-coated Kraft with Silicone Release  
 Adhesive Thickness: 74 µm  
 Liner Thickness: 100 µm

# 3.1

## First test results from 3M Beauchamps (95)

### Components

1 FEV7 CIP



1 Kapton comb  
1 connector



ACF 3M 7303 film  
width=5mm length= 25meters



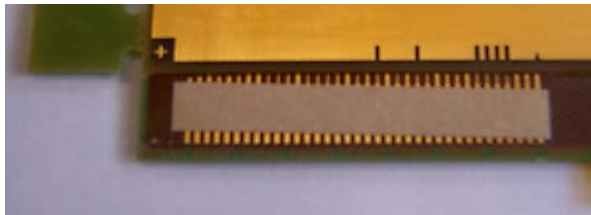
Miyachi thermode test bench



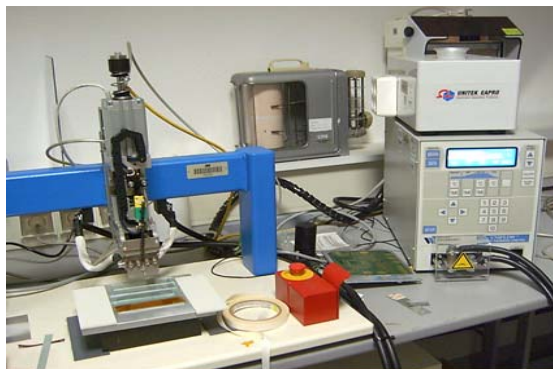
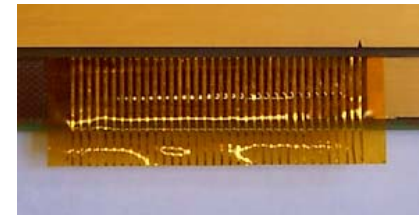
# 3.1 Process

The ACF 3M looks like double-sided tape

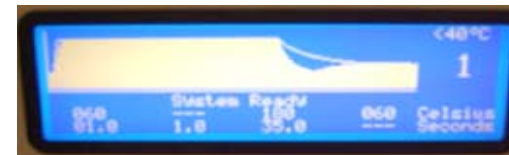
Put the ACF on FEV  
Remove the protect film (brown)



Positioning of the comb  
(It's possible to repeat the positioning)

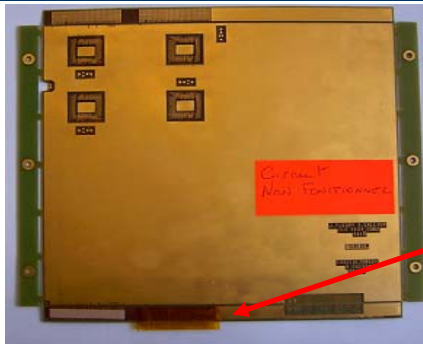


Using  
Myachi  
Thermode

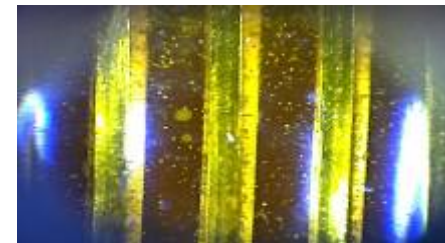
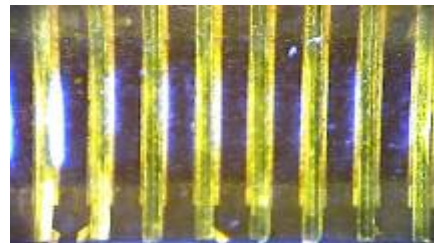


Temperature 150°C  
Time 25 seconds  
Pressure 18 Bar

## 3.1 Results



Kapton comb pictures with binocular



Results of electrical test made with a precision multimeter Keithley  
Resistance between wires in PCB = 0.2 ohms  
Isolation between wires in PCB =  $\infty$

Advantage of the ACF is:

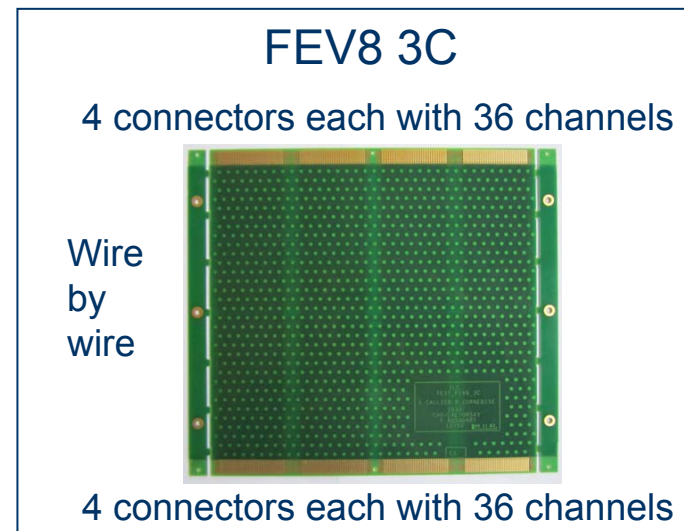
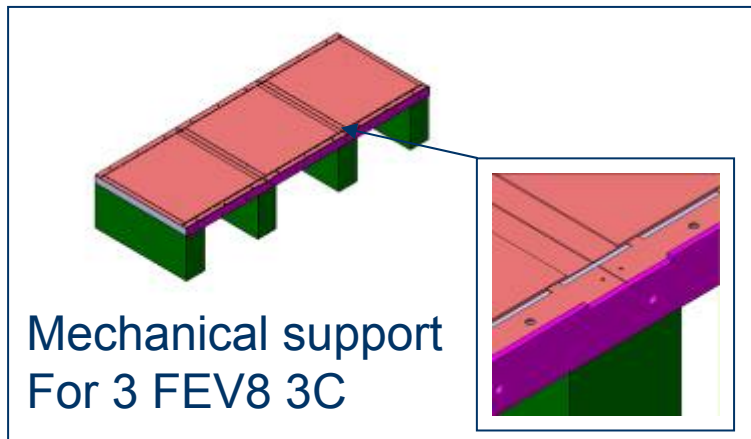
- Ease to use, low stress for PCBs
- **Industrialization of process is very easy**

R&D issues:

- Currently limited information on the lifetime,  
Requires further electrical and aging tests



## 3.2 Second test with the current thermode : Components



Kapton combs



4 connectors with 36 copper pads length=14mm width=0.5mm thickness 35 $\mu$ m

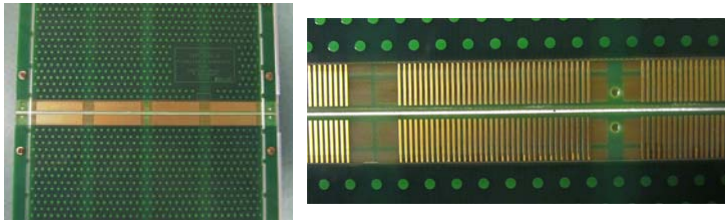
Thickness of kapton = 50 $\mu$ m

**Total thickness = 85 $\mu$ m**

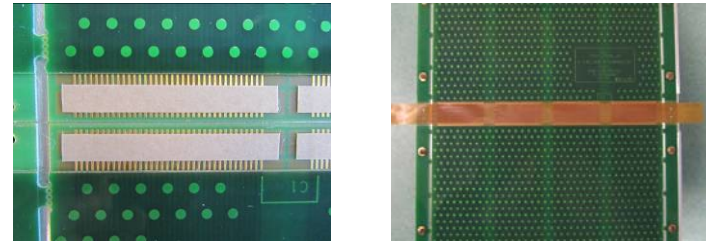
## 3.2

# Preparation of test bench and interconnect

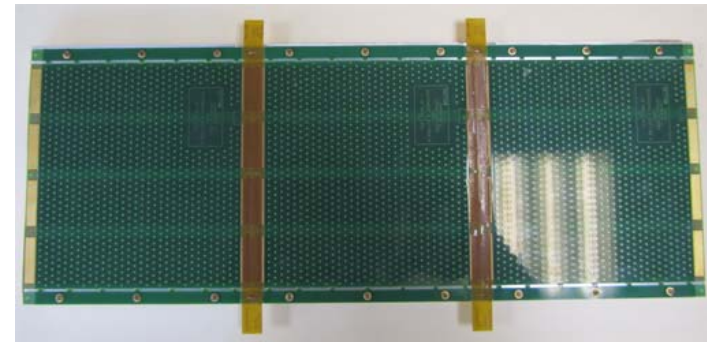
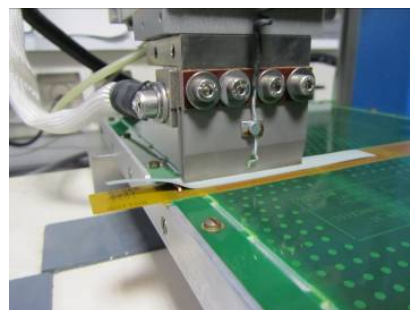
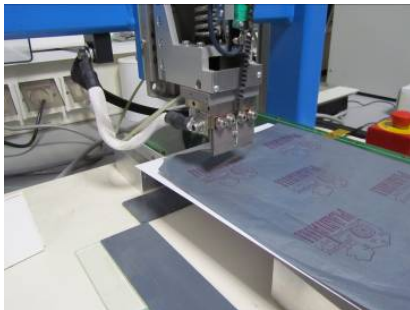
Positioning FEV8 3C  
to mechanical support



Put the ACF on boards and  
positioning kapton combs



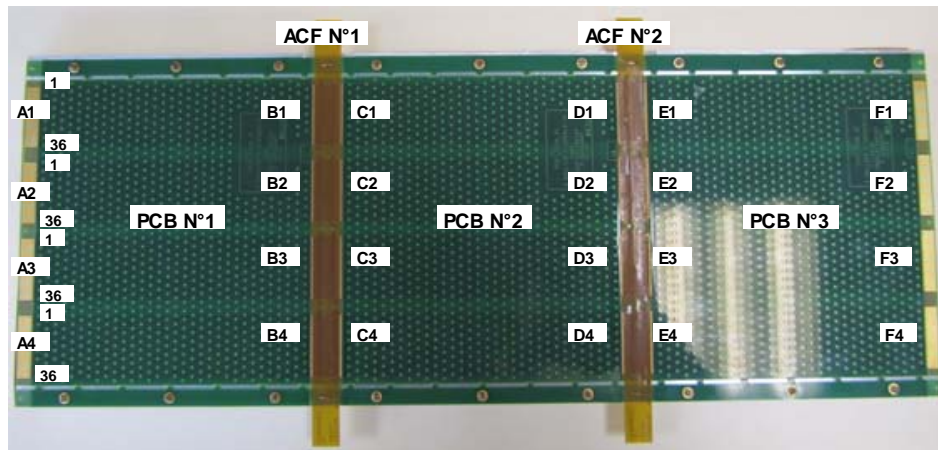
The test was done last March at 3M Beauchamps with the help of R. Cornat LLR



## 3.2

# Results of the second test

- Problems encountered during the test, we struggled to achieve the interconnection due to the lack of mechanical support planéarity FEV8 3c, and a non-adaptability of the nozzle of the Myachi thermode for our boards .
- Due to this problem many connections are defective, as shown in the results table,(résultats=values in ohms)(in red, bad values or not conduction)

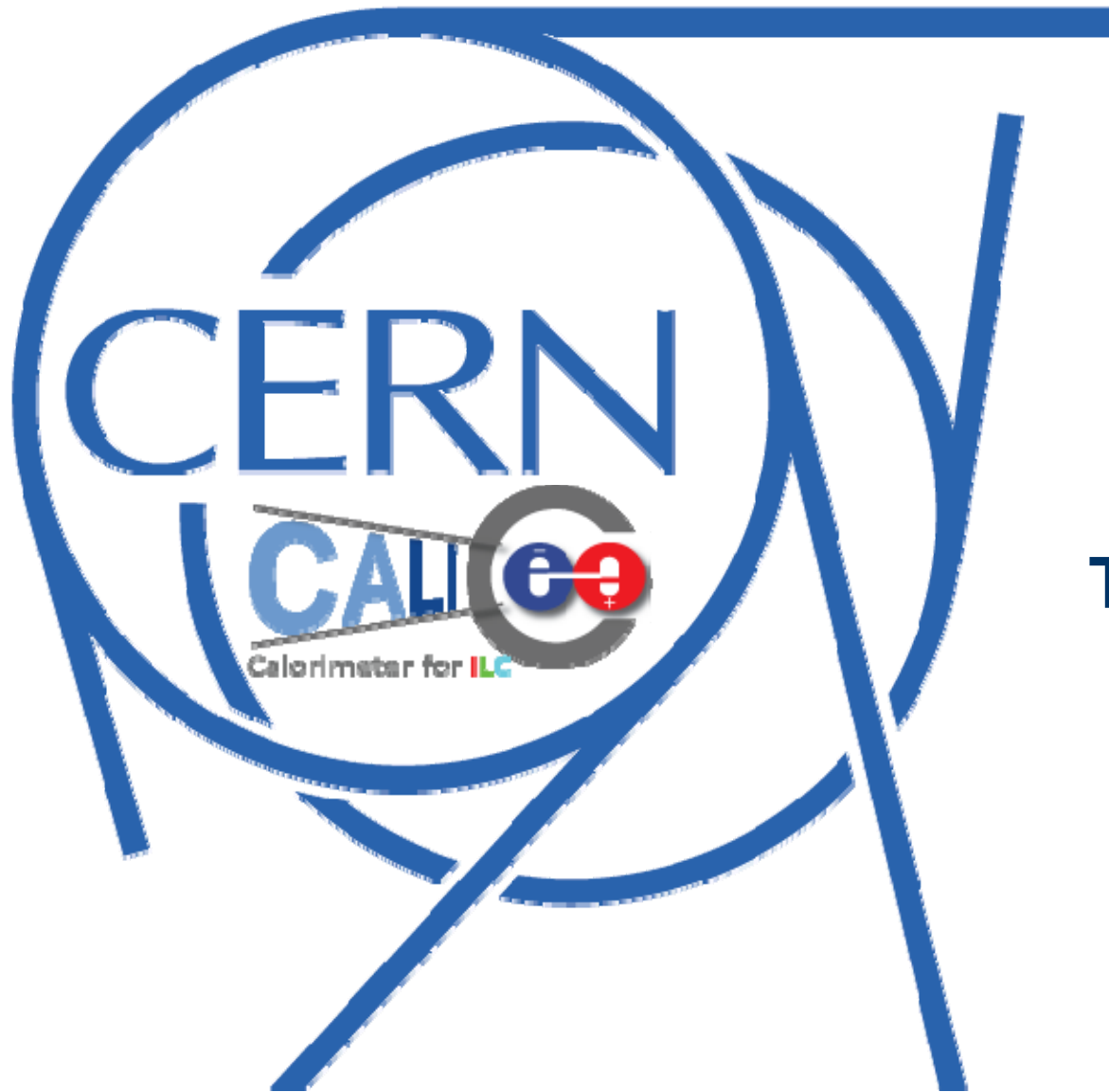


3 PCB N° 1-2-3 with 2 ACF wire by wire							
A1-F1	A2-F2		A3-F3		A4-F4		
Wire	Résultats	Wire	Résultats	Wire	Résultats	Wire	Résultats
1	1.3	1	1.5	1	1.2	1	1.2
2	2.6	2		2	1.2	2	1.4
3		3		3	1.3	3	1.3
4	11	4		4	1.3	4	1.3
5		5		5	1.2	5	1.3
6	8	6		6	1.3	6	1.3
7		7		7	1.3	7	1.3
8		8		8	1.3	8	1.3
9	1.8	9		9	1.3	9	1.3
10		10		10	1.3	10	1.3
11		11		11	1.3	11	1.3
12		12	2.7	12	1.3	12	1.3
13		13		13	1.3	13	1.3
14		14		14	1.3	14	1.3
15		15		15	1.3	15	1.3
16	21.5	16		16	1.3	16	1.3
17		17		17	1.3	17	1.3
18		18		18	1.4	18	1.3
19		19	17	19	1.3	19	1.3
20		20		20	1.3	20	1.3
21		21		21	1.3	21	1.3
22		22		22	1.3	22	1.4
23		23		23	1.3	23	1.3
24		24		24	1.3	24	1.9
25		25		25	1.3	25	1.3
26		26		26	1.4	26	1.6
27		27		27	1.3	27	1.4
28		28		28	1.3	28	2.2
29		29		29	1.3	29	1.4
30		30		30	1.5	30	1.6
31		31		31	1.3	31	2
32		32		32	1.3	32	3.8
33		33		33	1.6	33	2.3
34		34	2.5	34	1.5	34	1.7
35	3.3	35		35	1.5	35	3.4
36	2.4	36	2.5	36	1.8	36	1.9

## 3.3

### Next steps

- Making a new support at LAL with a good planéarity.
- Use for the new test 3FEV8 3C with glued below the square glass or waffers from LLR & LPNHE to test the resistance to pressure when we use the Myachi thermode.
- The next test will be conducted at 3M Beauchamp (95) or Myachi at St Germain en Laye (78)  
**but if we use this thermode unsuitable, we may have the same result, the easiest solution would be to make a thermode suited to our boards, but estimated costs, 15000 euros ...**
- Buy a freezer to store ACF (and beers)
- These operations are not yet scheduled.



**Thank's for your  
attention**